



<b>Title of Change:</b>	SPM32 1.3mil golden wire conversion to 1.2mil copper wire.	
<b>Proposed First Ship date:</b>	20 May 2021 or earlier if approved by customer	
<b>Contact Information:</b>	Contact your local ON Semiconductor Sales Office or <a href="mailto:Daisy.Zhi@onsemi.com">Daisy.Zhi@onsemi.com</a>	
<b>PCN Samples Contact:</b>	Contact your local ON Semiconductor Sales Office or <a href="mailto:PCN.samples@onsemi.com">PCN.samples@onsemi.com</a> . Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
<b>Type of Notification:</b>	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <a href="mailto:PCN.Support@onsemi.com">PCN.Support@onsemi.com</a>	
<b>Marking of Parts/ Traceability of Change:</b>	Marking no change and traceability follow date code	
<b>Change Category:</b>	Assembly Change	
<b>Change Sub-Category(s):</b>	Material Change	
<b>Sites Affected:</b>		
<b>ON Semiconductor Sites</b>	<b>External Foundry/Subcon Sites</b>	
ON Semiconductor Suzhou, China	None	
<b>Description and Purpose:</b>		
TO3P5L bonding wire material conversion form 1.3mil gold wire to 1.2mil copper wire.		
	<b>Before Change Description</b>	<b>After Change Description</b>
Bond Wire	1.3mil gold wire	1.2mil copper wire
There is no product marking change as a result of this change.		



**Qualification Plan:**

Discrete PCN

QV DEVICE NAME: FSAM50SM60A

PACKAGE: SPM32

REL TEST RMS:

Test	Specification	Condition	Interval
HTSL	JESD22-A103	Ta =Max rated storage temp for device	1,008/2,016 hrs
TC	JESD22-A104	Ta= -40°C to +125°C	500/1,000 cyc
THB	JESD22-A101	Temp = +85°C; RH = 85%, 80% rated Volt (100V max), Vcc=15V, Vin=5V	1008/2,016hrs
UHASt	JESD22-A118	Temp = 130C, RH=85%, ~ 18.8 psig	96hr
RSH	JESD22-B106	Ta=265C 10 sec dwell, electrical test before and after	10s
DPA	AEC-Q101-004 Section 4	Destructive Physical Analysis, Post TC and THB	

Estimated date for qualification completion: 13 January 2021

**List of Affected Parts:**

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
FPAM50LH60G	FSAM50SM60A
FPAM30LH60	FSAM50SM60A
FPAM50LH60	FSAM50SM60A
FSAM75SM60A	FSAM50SM60A
FSAM50SM60A	FSAM50SM60A



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## Appendix A: Changed Products

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Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
FPAM30LH60		FSAM50SM60A		
FSAM50SM60A		FSAM50SM60A		
FSAM75SM60A		FSAM50SM60A		